



SA115

SA115 AI Base CCL

特点

- 优良的散热性
- 优秀的耐热性和绝缘可靠性
- 优秀的加工性
- 高 CTI

FEATURES

- Superior Heat Dissipation
- Excellent Thermal Reliability and Insulation Reliability
- Excellent Processability
- High CTI

应用领域

适用于大功率LED照明、电源电路、LED TV等。

APPLICATIONS

Suitable for high-power LED lighting, power supply circuit, LED TV, and etc.

GENERAL PROPERTIES

Test Item	Treatment Condition	Unit	Property Data (Typical Value)
Thermal Stress	288°C, solder dipping	min	10
	288°C, solder floating	min	40
Peel Strength (1OZ Cu.)	After thermal shock (10 sec@288°C)	N/mm	1.2
Dielectric Breakdown Voltage, AC	D-48/50+D-0.5/23	kV	6.0
Thermal Conductivity	Prepreg ASTM D5470	W/(m·K)	1.5
Thermal Impedance		K·cm ² /W	0.75
Hi-pot	DC	V	4000
	AC		2000
Surface Resistance	After moisture resistance	MΩ	10 ⁷
	E-24/125	MΩ	10 ⁶
Volume Resistance	After moisture resistance	MΩ·cm	10 ⁸
	E-24/125	MΩ·cm	10 ⁷
Dielectric Constant	C-24/23/50,1MHz	-	5.2
	C-24/23/50,1GHz	-	4.8
Dissipation Factor	C-24/23/50,1MHz	-	0.010
	C-24/23/50,1GHz	-	0.012
CTI	IEC60112 Method	V	600
Glass Transition Temperature	DSC	°C	130
CTE(Z-axis)	Before Tg TMA	ppm/°C	22
Decomposition Temperature(Td)	TGA(5% Weight Loss)	°C	350
Flammability	UL-94	class	V-0

* Typical Value is based on specimen of 1.0mm Al / 100 μm dielectric/ 1 OZ Cu

Explanations: C = 湿热处理条件 Humidity conditioning.

E = 恒温处理条件 Temperature conditioning.

D = 浸泡于蒸馏水 Immersion conditioning in distilled water.



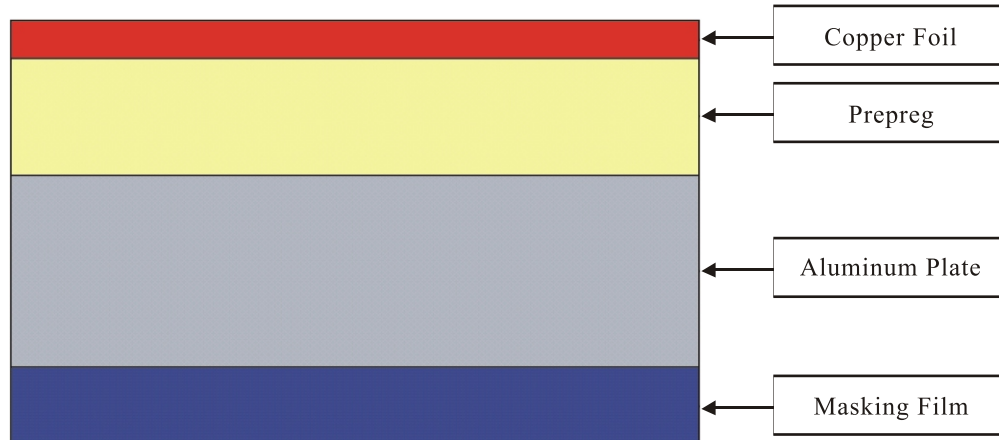
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PURCHASING INFORMATION

	Material	Type
Cu	Hoz, 1oz, 2oz, 3oz, 4oz, 6oz, 10oz	
Dielectric Layer (Prepreg)	106, 1080, 2116	
Base Metal Plate	1060 Al	0.3-3.0mm
	5052 Al	
	6061 Al	
Masking Film	PET/PI Film	2.5 mil
Standard Size	1020mmX1220mm (Other sizes are available upon request)	

SA115 STRUCTURE



EXCELLENT BREAKDOWN VOLTAGE

